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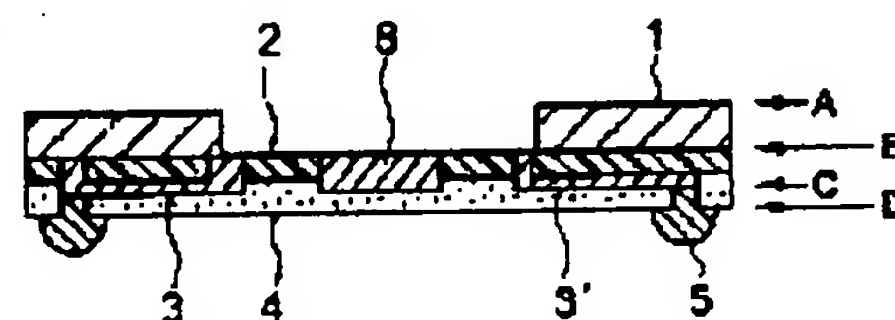
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(54) LEAD FRAME, MANUFACTURE THEREOF AND SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a lead frame which can be manufactured through simplified processes.

SOLUTION: A lead frame is equipped with a conductive board 1, leads 3 and 3' which are two-dimensionally formed by plating on the conductive board 1, an insulating film 4 which is formed on the surface of the board 1 where the leads 3 and 3' are provided, openings provided to the insulating film 4 corresponding to the leads 3 and 3' so as to make them exposed, external terminals 5 each provided to the openings, and a die pad 6 which is obtained by selectively etching the conductive board 1 so as to support a semiconductor element, where the conductive board 1 functioning as a feeder layer when plating is carried out is made to serve as a reinforcing plate. Therefore, a stiffener serving as a reinforcing plate is not required to be bonded through a separate process, and a stiffener and a ground layer can be formed through the same process with which a wiring layer and a grounding layer are formed.



LEGAL STATUS

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(3) 請求項 3 5 及び 3 6 に係る発明について

・引用文献：1—6

リードフレームの製法として、エッチングやスタンピングは本願出願前より慣用的に行われているものにすぎない。

引用文献等一覽

1. 特開平05-129473号公報
2. 特開昭60-195957号公報
3. 特開平06-140563号公報
4. 特開平01-251747号公報
5. 特開平10-163401号公報
6. 特開昭63-067762号公報

先行技術文献調査結果の記録

・調査した分野 I P C第7版 H01L 23／12， 23／28，
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・先行技術文献 特開平10-012773号公報
特開昭63-054759号公報

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この拒絶理由通知書についてのお問い合わせ先

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